

## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	SEMICONDUCTOR PACKAGE WITH HEAT SINK	
Application Type:	regular, utility	
Attorney Docket Number:	1007-042	
Correspondence address:		
Customer Number:	22898	*22898*
Priority Data:		
Doc.No: 092105857; Country - TW; Date: 2003-03-18 us-priority-claimed		
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22898      \*22898\*

as my attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

**Publication Information:**

Suggested Figure for Publication – FIG. 1

Suggested Classification –

Suggested Technology Center –

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